

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at <u>www.onsemi.com</u>

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any product sherein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees



August 2014

FCP20N60 / FCPF20N60 N-Channel SuperFET® MOSFET

600 V, 20 A, 190 mΩ

Features

- 650V @ T_J = 150°C
- Typ. R_{DS(on)} = 150 mΩ
- Ultra Low Gate Charge (Typ. Q_q = 75 nC)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 165 pF)
- · 100% Avalanche Tested

Applications

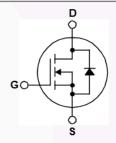
- Solar Inverter
- · AC-DC Power Supply

Description

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications.







Absolute Maximum Ratings

Symbol		Parameter		FCP20N60	FCPF20N60	Unit
V _{DSS}	Drain-Source Volta	age		6	00	V
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		20 12.5	20* 12.5*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	60	60*	Α
V _{GSS}	Gate-Source Volta	age		±	30	V
E _{AS}	Single Pulsed Ava	alanche Energy	(Note 2)	6	90	mJ
I _{AR}	Avalanche Curren	t	(Note 1)		20	Α
E _{AR}	Repetitive Avalance	che Energy	(Note 1)	2	0.8	mJ
dv/dt	Peak Diode Reco	very dv/dt	(Note 3)	4	1.5	V/ns
P_{D}	Power Dissipation	(T _C = 25°C) - Derate Above 25°C		208 1.67	39 0.3	W/°C
T _{J,} T _{STG}	Operating and Sto	rage Temperature Range		-55 to	+150	°C
T _L	Maximum Lead Te 1/8" from Case for	emperature for Soldering, r 5 Seconds		3	00	°C

^{*}Drain current limited by maximum junction temperature.

Thermal Characteristics

Symbol	Parameter	FCP20N60	FCPF20N60	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.6	3.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP20N60	FCP20N60	TO-220	Tube	N/A	N/A	50 units
FCPF20N60	FCPF20N60	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	eteristics					
Desire to Course Descriptions Veltage		$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}, T_J = 25^{\circ}\text{C}$	600	-	-	V
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu\text{A}, V_{GS} = 0 \text{V}, T_J = 150^{\circ}\text{C}$	-	650	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.6	-	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	V _{GS} = 0 V, I _D = 20 A	-	700	-	٧
1	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1	
IDSS	Zero Gate voltage Drain Current	$V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	10	μA
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 10 A	-	0.15	0.19	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 10 A	-	17	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 25 V V 20 V	-	2370	3080	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	1280	1665	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11 12	-	95	-	pF
Coss	Output Capacitance	V _{DS} = 480 V, V _{GS} = 0 V, f = 1 MHz	-	65	85	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	165	-	pF
Qg	Total Gate Charge at 10V	V _{DS} = 480 V, I _D = 20 A,	-	75	98	nC
Q _{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	-	13.5	18	nC
Q _{qd}	Gate to Drain "Miller" Charge	(Note 4)	-	36	-	nC

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		/-	62	135	ns
t _r	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_D = 20 \text{ A},$	-	140	290	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_G = 25 \Omega$	-	230	470	ns
t _f	Turn-Off Fall Time	(Note 4)	-	65	140	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diod	Maximum Continuous Drain to Source Diode Forward Current		-	20	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Fo	Maximum Pulsed Drain to Source Diode Forward Current		/-	60	Α
V_{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 20 A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 20 A,	-	530	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs	-	10.5	-	μC

Notes:

- 1: Repetitive rating: pulse-width limited by maximum junction temperature.
- 2: $I_{AS} = 10 \text{ A}$, $V_{DD} = 50 \text{ V}$, $R_{G} = 25 \Omega$, starting $T_{J} = 25^{\circ}\text{C}$. 3: $I_{SD} \le 20 \text{ A}$, $di/dt \le 200 \text{ A/}\mu\text{s}$, $V_{DD} \le BV_{DSS}$, starting $T_{J} = 25^{\circ}\text{C}$.
- 4: Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

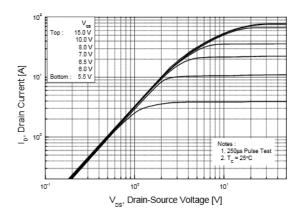


Figure 2. Transfer Characteristics

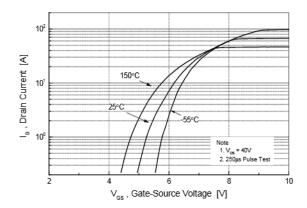


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

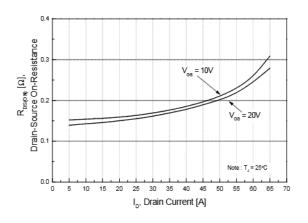


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

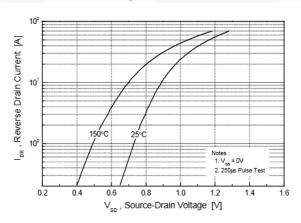


Figure 5. Capacitance Characteristics

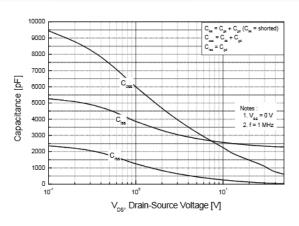
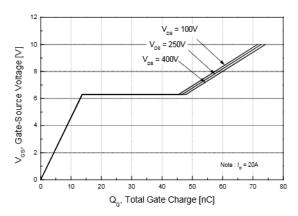


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

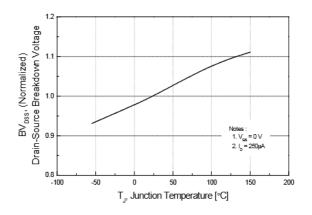


Figure 8. On-Resistance Variation vs. Temperature

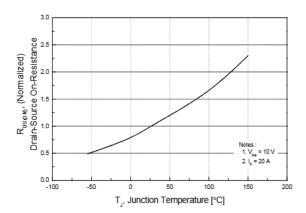


Figure 9-1. Maximum Safe Operating Area for FCP20N60

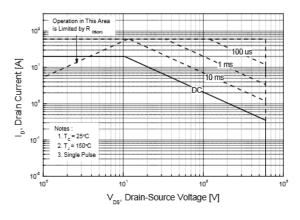


Figure 9-2. Maximum Safe Operating Area for FCPF20N60

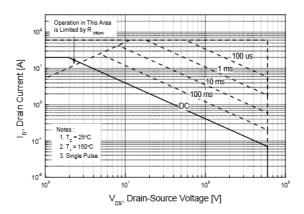
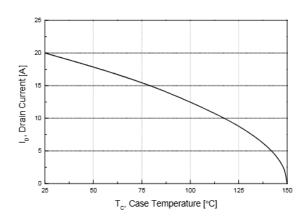


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 11-1. Transient Thermal Response Curve for FCP20N60

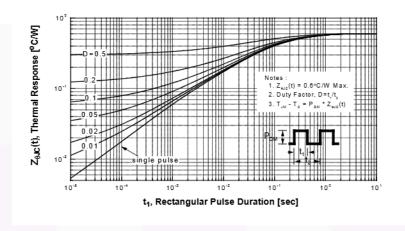
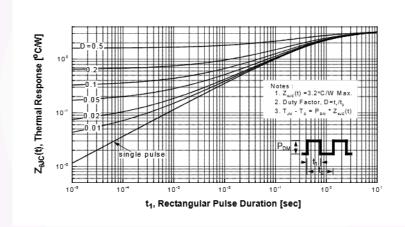


Figure 11-2. Transient Thermal Response Curve for FCPF20N60



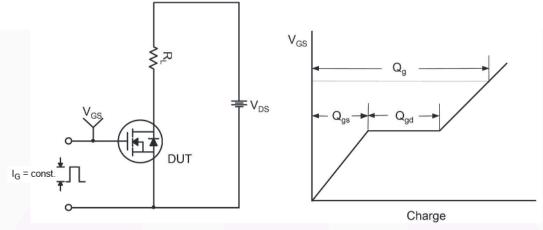


Figure 12. Gate Charge Test Circuit & Waveform

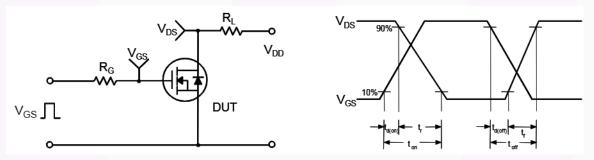


Figure 13. Resistive Switching Test Circuit & Waveforms

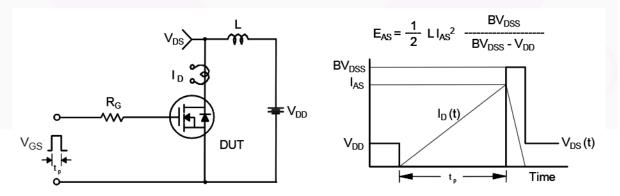


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

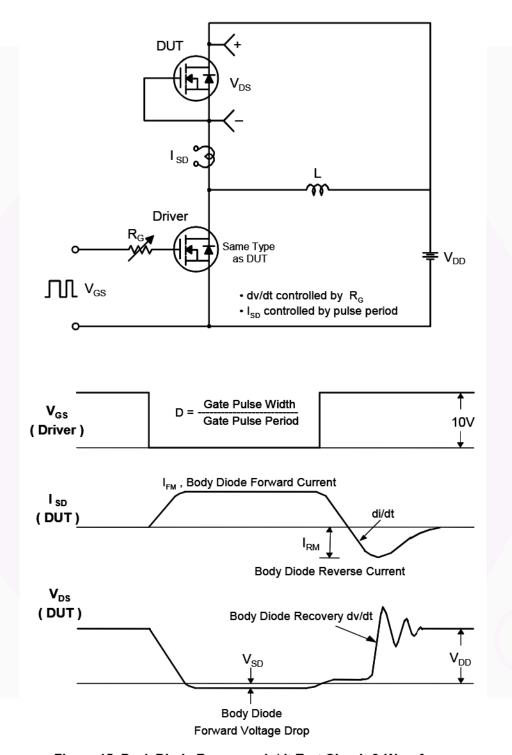
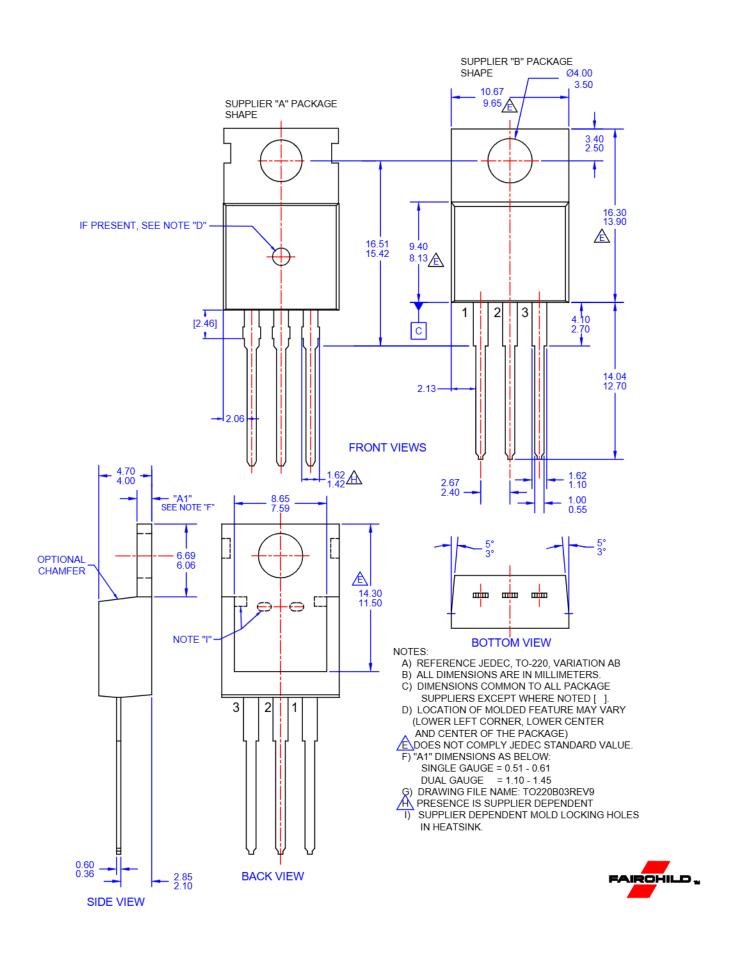
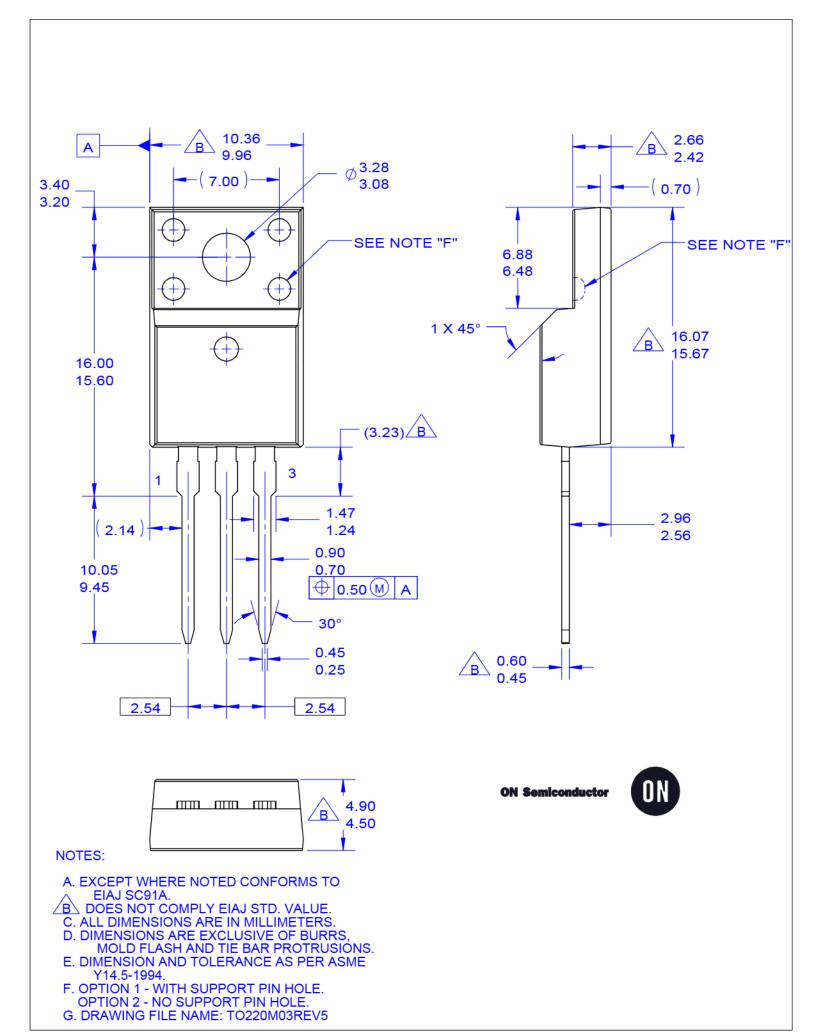


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms





ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized dapplication, Buyer shall indemnify and ho

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative